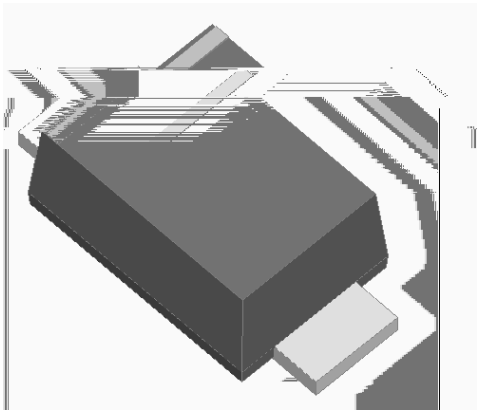
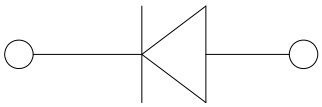
Surface Mount General Purpose Rectifier





Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF m ` Terminals

Device marking code			**1ML**
Repetitive peak reverse voltage	V_{RRM}	V	1000
Maximum RMS voltage	V_{RMS}	V	700
Average rectified output current @60Hz sine wave, resistance load, Tc=80	Io	A	1.0
Surge(non-repetitive)forward current @ 60Hz half-sine wave,1 cycle, T_J=25	I_{FSM}	A	18
Current Squared Time @1ms≤t<8.3ms Tj=25	I^2t	A^2s	1.34
Storage temperature	T_{STG}		-55 ~+150
Junction temperature	T_J		-55 ~+150

■Electrical Characteristics Tj=25 Unless otherwise specified

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	FMG1M
Maximum instantaneous forward voltage drop per diode	V_F	V	I_F=1.0A	1.1
Typical junction capacitance	C_J	pF	V_R=4V,1 MHz	3
Maximum DC reverse current at rated DC blocking voltage per diode	I_{RRM}	μA	T_J=25	5
			T_J=125	50

■Thermal Characteristics T_a=25 Unless otherwise specified

PARAMETER	SYMBOL	UNIT	FMG1M
Thermal resistance	$R_{\theta J-A}$	/W	270 [1]
	$R_{\theta J-L}$		85 [1]
	$R_{\theta J-C}$		60 [2]

Note:
(1) Thermal resistance between junction and ambient and between junction and lead mounted on P.C.B without copper pad areas.
(2) Thermal resistance between junction and cathode tab solder point.

■ Characteristics(Typical)

SБ ˆ

Instantaneous Forward Current(A)

■ Outline Dimensions

SOD-323FL		
Dim	Min	Max
A	1.05	1.45

Disclaimer

The information presented in this document is for reference onl